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(54) Title: MEMS PRESSURE SENSOR BUILT USING THE BEOL METAL LAYERS OF A SOLID-STATE SEMICONDUCTOR PROCESS

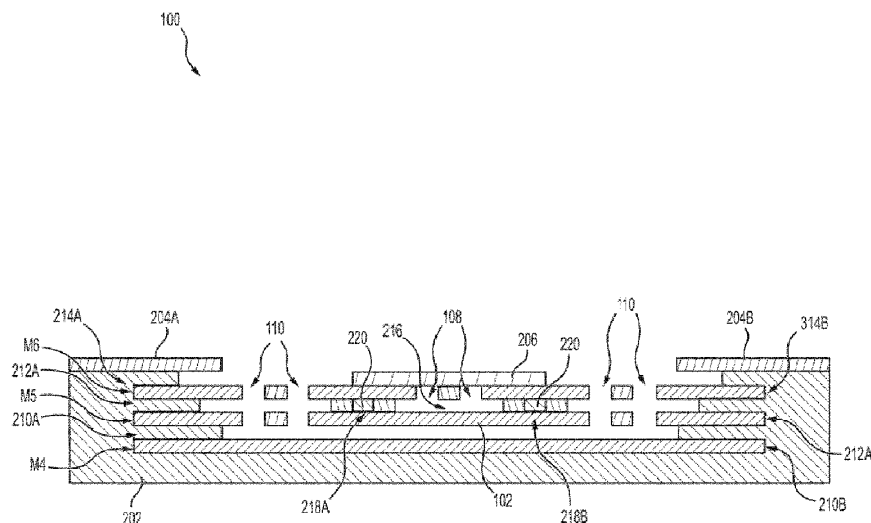


FIG. 2

(57) Abstract: A MEMS pressure sensor is provided having a membrane made with one of plurality of metal layers. A lid is positioned above the membrane and connected to a plurality of cavity walls at distal ends of the membrane. The lid includes an array of holes positioned on a region of the lid. A fixed metal electrode is positioned below the lid.

[Continued on next page]

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